



MediaTek Inc.

No.1, Dusing 1st Rd., Hsinchu Science Park, Hsinchu City 300, Taiwan

Tel: +886-3-567-0766 Fax: +886-3-5787610

www.mediatek.com

Sep. 4, 2025

To: Elisabetta Comin, Kimmo Kymalainen
Mobile Competence Centre (ETSI)
650, Route Des Lucioles
Sophia-Antipolis, France

Letter of support and nomination of Mr. Daiwei Zhou for 3GPP CT6 Vice Chair.

Dear Ms. Elisabetta Comin, Mr. Kimmo Kymalainen,

On behalf of MediaTek Inc. I am delighted to nominate Daiwei Zhou for the position as 3GPP CT WG6 Vice Chair, with election at 3GPP CT6 #124, in November 2025. He will represent MediaTek Inc. / ETSI / Corp OP: General. As a Smart Card Application technical expert, Daiwei has been actively participating in 3GPP CT6 since 2012. With his long experience and his dedication to standardization work, we are confident that Daiwei Zhou can be beneficial for the ongoing evolution of standards towards 6G.

In proposing Mr. Daiwei Zhou for this position, MediaTek Inc. will provide all support required for Daiwei Zhou in the role as 3GPP TSG CT WG6 Vice Chair. He is aware of applicable laws and regulations, will be further trained as needed, and shall comply with all applicable antitrust/competition laws and regulations while acting in his capacity as TSG CT WG6 Vice Chair.

Yours Sincerely

A handwritten signature in blue ink, appearing to read "H.C. Hwang".

HC Hwang
General Manager,
Wireless Communication System and Partnership
Mediatek Inc.

Brief Curriculum Vitae of Mr. Daiwei Zhou

Daiwei Zhou has over 17 years' experience in Smart Card Application (UICC/USIM/USAT) development and testing in the wireless communication industry. He has actively participated in the SDO and Certification Forums since 2012.

Daiwei Zhou represents MediaTek Inc. attending 3GPP TSG CT WG6, RAN WG5 and Global Certification Forum (GCF) meetings since 2017. Prior to employment at MediaTek Inc., Daiwei worked for China Academy of Information and Telecommunication (CAICT) with similar position to continuously participate 3GPP CT6, RAN5 and GERAN meetings. He has been the rapporteur of many Work Items in 3GPP CT6, RAN5, GERAN and GCF with industry level recognition of technical leadership and expertise.

Daiwei holds a BSc. degree in Communication Engineering from Beijing University of Posts and Telecommunications, China.